

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yu-Rung HSU</td> <td>02/09/2010</td> </tr> <tr> <td>Chen-Hua YU</td> <td>02/09/2010</td> </tr> <tr> <td>Chao-Cheng CHEN</td> <td>02/09/2010</td> </tr> </tbody> </table>		Name	Execution Date	Yu-Rung HSU	02/09/2010	Chen-Hua YU	02/09/2010	Chao-Cheng CHEN	02/09/2010				
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CORRESPONDENCE DATA													
<p>Fax Number: (214)200-0853</p> <p><i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000</p> <p>Email: eppsl@haynesboone.com</p> <p>Correspondent Name: HAYNES AND BOONE, LLP IP Section</p> <p>Address Line 1: 2323 Victory Avenue</p> <p>Address Line 2: Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	24061.1326												
NAME OF SUBMITTER:	David M. O'Dell												
Total Attachments: 2													

CH \$40.00 12645834

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PATENT
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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|--|
| (1) | Yu-Rung Hsu | of | 7F-1, No. 2, Lane 12, Daxue Road, East District
Tainan City 701, Taiwan, R.O.C. |
| (2) | Chen-Hua Yu | of | No. 3, 38 Waterfront Road 2
Hsin-Chu, Taiwan, R.O.C. |
| (3) | Chao-Cheng Chen | of | #46 3F-2, Lui-Sui Road
Shin-Chu City, Taiwan, R.O.C. |

have invented certain improvements in

**METHOD OF FABRICATING STRAINED STRUCTURE
IN SEMICONDUCTOR DEVICE**

for which we filed an application for Letters Patent of the United States of America on December 23, 2009, as U.S. Serial No. 12/645,834; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2009-0352 / 24061.1326

Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yu-Rung Hsu

Residence Address: 7F-1, No. 2, Lane 12, Daxue Road, East District
Tainan City 701, Taiwan, R.O.C.

Dated: 2010.02.09

Yu-Rung Hsu
Inventor Signature

Inventor Name: Chen-Hua Yu

Residence Address: No. 3, 38 Waterfront Road 2
Hsin-Chu, Taiwan, R.O.C.

Dated: 2/9/10

Chen-Hua Yu
Inventor Signature

Inventor Name: Chao-Cheng Chen

Residence Address: #46 3F-2, Lui-Sui Road
Shin-Chu City, Taiwan, R.O.C.

Dated: 2010.02.09

Chao-Cheng Chen
Inventor Signature